

Electronic Patent Application Fee Transmittal

Application Number:	10565587			
Filing Date:	22-Feb-2007			
Title of Invention:	Copper Foil with Ultra Thin Adhesive Layer, and a Method for Manufacturing the Copper Foil with Ultra Thin Adhesive Layer			
First Named Inventor/Applicant Name:	Tetsuro Sato			
Filer:	Stephen M. Roylance/Annette Limberg			
Attorney Docket Number:	3209-111			

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 1 month with \$0 paid	1251	1	130	130
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130